

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
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Seok-yong Hong	04/10/2013
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13864594
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Date:	04/17/2013
Total Attachments: 2	
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OP \$40.00 13864594

ASSIGNMENT

Attorney Docket No.

DOCKET NO.

First Named Inventor: Hee-Yeon Kim

Title: METHOD FOR PREPARING METAL-CARBON COMPOSITE OF CORE-SHELL STRUCTURE THROUGH SIMULTANEOUS VAPORIZATION AND METAL-CARBON COMPOSITE OF CORE-SHELL STRUCTURE PREPARED THEREBY

WHEREAS, Hee-Yeon Kim of 305-201, Central Park Apt., Munhwa 1-dong, Jung-gu, Daejeon 301-131, Republic of Korea; and Seok-yong Hong of 101-1502, Gyeongseong Keun Maeul Apt., Galma 2-dong, Seo-gu, Daejeon 302-182, Republic of Korea, have invented certain new and useful improvements as described in an application entitled METHOD FOR PREPARING METAL-CARBON COMPOSITE OF CORE-SHELL STRUCTURE THROUGH SIMULTANEOUS VAPORIZATION AND METAL-CARBON COMPOSITE OF CORE-SHELL STRUCTURE PREPARED THEREBY for Letters Patent of the United States, the application having been executed on even date herewith, and/or being identifiable in the United States Patent and Trademark Office by Application No. 13/864,594, filed April 17, 2013; and

WHEREAS, KOREA INSTITUTE OF ENERGY RESEARCH, a corporation organized and existing under the laws of Republic of Korea, and having offices at 102 Gajeong-ro, Yuseong-gu, Daejeon 305-343, Republic of Korea, ("Assignee") is desirous of acquiring the entire right, title and interest in and to the invention, the application, and any and all Letters Patent or similar legal protection, foreign or domestic, to be obtained therefor;

NOW, THEREFORE, for good and valuable consideration, the receipt and adequacy of which is hereby acknowledged, I transfer to Assignee, its successors and assigns, my entire right, title and interest in and to the invention, the above-identified application, corresponding domestic and foreign applications, all Letters Patent or similar legal protection issuing thereon, and all rights and benefits under any applicable treaty or convention; and I authorize the Commissioner of Patents and Trademarks of the United States or foreign equivalent thereof to issue the Letters Patent or similar legal protection to the Assignee.

I authorize the Assignee, its successors and assigns, to insert in this instrument the filing date and application number of the application when ascertained.

I authorize the Assignee, its successors and assigns, or anyone it may properly designate, to apply for Letters Patent or similar legal protection, in its own name if desired, in any and all foreign countries.

I represent to the Assignee, its successors and assigns, that I have not and shall not execute any writing or do any act whatsoever conflicting with this Assignment. I, my executors or administrators, will at any time upon request, without additional consideration, but at the expense of the Assignee, its successors and assigns, execute such additional writings and do such additional acts as the Assignee, its successors and assigns, may deem desirable to perfect its enjoyment of this grant, and render all assistance in making application for and obtaining, maintaining, and enforcing the Letters Patent or similar legal protection on the invention in any and all countries.

Hee yeon Kim
Inventor Signature: Hee-Yeon Kim

April 10, 2013
Date

Seck yong Hong
Inventor Signature: Seck-yong Hong

April 10, 2013
Date

Inventor Signature:

Date

Inventor Signature:

Date

Inventor Signature:

Date

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